

Docket No.: 060188-0649



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
Eigo SHIRAKASHI, et al.	:	Confirmation Number: 5843
Application No.: 10/665,015	:	Group Art Unit: 3723
Filed: September 22, 2003	:	Examiner: McDonald, Shantese L.

For: METHOD FOR POLISHING SEMICONDUCTOR WAFER AND POLISHING PAD FOR THE SAME

**AMENDMENT UNDER 37 C.F.R. §1.114**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 25, 2005, having a three-month shortened statutory period for response set to expire June 25, 2005, please amend the above-identified application as follows: